

# GT25

## Graphene Based Thermal Interface Material and Heatspreader

### Features:

- Good flexibility
- Compressible
- Easy to use

### Applications:

IGBT, GPU, CPU, LED, RF, Opto and power module cooling

Order status: Large amount available now

### Description:

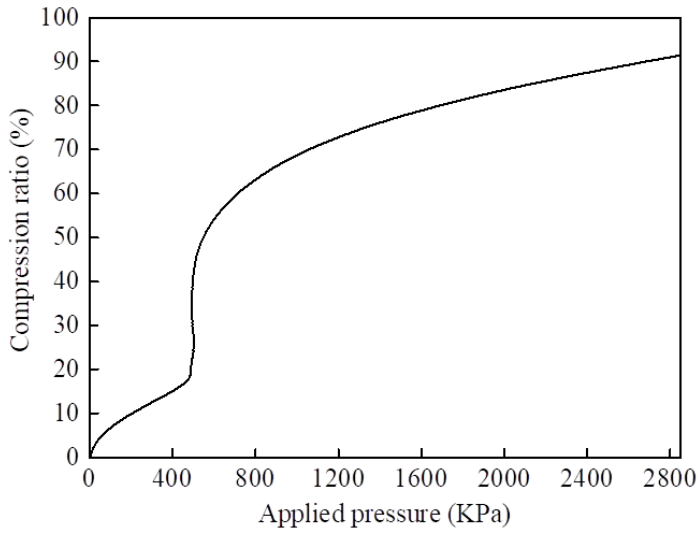
With highly flexible, compressible and smooth structures, GT25 can provide complete physical contact between two surfaces as well as minimizing the contact resistance to heat flow, therefore, lead to superior effective thermal conductivity and low thermal resistance. In addition, the GT25 has advantages of low weight, low complexity during assembly and good maintainability. GT25 thus opens new opportunities for addressing large heat dissipation issues in electronics and other high power driven systems.

Physical Properties	Value	Units	Test Method
Size	□ 4*4	cm <sup>2</sup>	
Thickness	0.25-0.5(± 15%)	mm	
Roughness	<5	%	
Color	Grey		
Filler Material	Graphene		
Density	0.6	g/cm <sup>3</sup>	
Compressibility	20-30	%	ASTM
Recovery	15-20	%	ASTM
Compressive Strength	500	KPa	ASTM
Temperature Range	-40 to 200	°C	
Bulk Through-plane Thermal Conductivity	350-450	W/mK	LFA447
Effective Thermal Conductivity	10-12 (100 KPa) 24-25(400 KPa)	W/mK	ASTM
Thermal Resistance	50-70 (100 KPa) 20-30 (400 KPa)	Kmm <sup>2</sup> /W	ASTM
Bulk In-plane (parallel to alignment) Thermal Conductivity	350-450	W/mK	LFA447
Bulk In-plane (perpendicular to alignment) Thermal Conductivity	1-2	W/mK	LFA447
Specific Heat	0.2-0.3	J/g.K	Hotdisk
Minimum in-plane tensile strength	50	KPa	ASTM

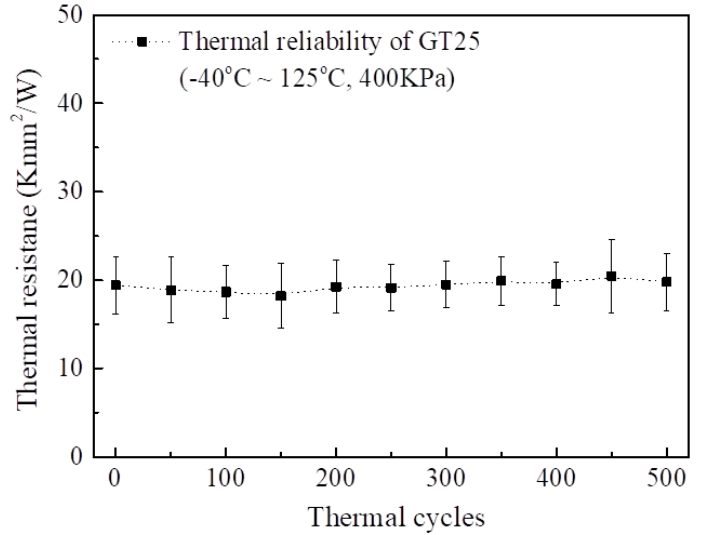
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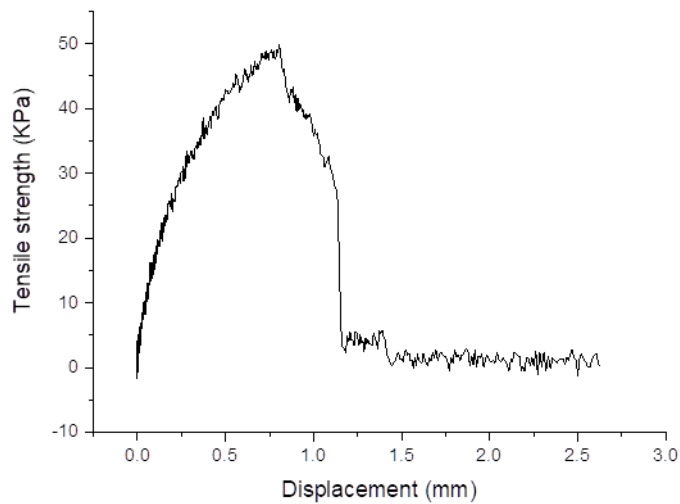
Compression ratios of GT25 at different pressures:



Thermal reliability of GT25



Tensile strength curve of GT25 at in-plane direction



Thermal resistance curve of GT25 (500 μm) at different pressures.

